



Mattson Technology Introduces Helios XP(TM) and Extends RTP Leadership Into Logic and Foundry Market

Ships Helios XP(TM) System to a Leading Foundry Customer for Advanced Anneal Processing

FREMONT, CA, Aug 31, 2009 (MARKETWIRE via COMTEX News Network) -- Mattson Technology, Inc. (NASDAQ: MTSN), a leading supplier of advanced process equipment used to manufacture semiconductors, today announced the release of the Helios XP(TM) system, the company's latest innovation targeted to meet the stringent requirements of advanced rapid thermal processing (RTP) for 45nm node and below. The third generation of 300-millimeter RTP tools strengthens Mattson's RTP market leadership for advanced chip manufacturing, extending its strong memory market position into logic and foundry segments. The company noted that its Helios XP system has been in qualification at a major IC manufacturer and it recently shipped a system to a leading foundry customer for advanced anneal processing.

Senior Vice President and General Manager of Mattson Technology's Thermal Products Group, Andreas Toennis, noted, "We are extremely pleased with the Helios XP's performance against leading customers' most advanced anneal application requirements. Helios XP offers the industry's first RTP processing capabilities at temperatures down to 220 degrees Celsius and below, enabling the advancement of future technology node development including the formation of advanced silicides. In addition, temperature and ambient controls have greatly improved for exceptional within-wafer uniformity and wafer-to-wafer repeatability required for 45nm and below technology nodes."

Toennis continued, "Our customers continue to demand technology solutions required to advance to the next technology node while maintaining the lowest possible cost performance. We listened to those challenges and acted. Even during the industry's worst downturn we invested in advancing the RTP technology providing unique and enabling solutions to the industry. With the introduction of Helios XP, Mattson's RTP position is stronger than ever. Helios XP delivers the advanced capabilities our customers require at the lowest cost-of-ownership, and the shipment of the system to a leading foundry customer is a testament of the traction we are gaining in the leading-edge logic segment. We look forward to working closely with the customer and continue to validate their confidence in Mattson and our capabilities in meeting their advanced process requirements."

About Helios XP(TM)

Helios XP combines Mattson Technology's production proven Helios system with advanced process capabilities needed for 45nm technology node and below. The system features an advanced temperature control for increased within-wafer uniformity and wafer-to-wafer repeatability. Helios XP incorporates proprietary design features, including dual-sided wafer heating to improve device yield by reducing pattern-related temperature effect. Helios XP offers the industry's most advanced low temperature thermal processing capability, as well as high temperature for spike anneal and wafer manufacturing thermal applications. Complete with superior ambient control and new process gas arrangement, Helios XP offers the most advanced thermal processing solution for the industry.

About Mattson Technology, Inc.

Mattson Technology, Inc. designs, manufactures and markets semiconductor wafer processing equipment used in the fabrication of integrated circuits. We are a leading supplier of plasma and rapid thermal processing equipment to the global semiconductor industry. Through manufacturing and design innovation, we have produced technologically advanced systems that provide productive and cost effective solutions for customers fabricating current- and next-generation semiconductor devices. For more information, please contact Mattson Technology, Inc., 47131 Bayside Parkway, Fremont, CA, 94538. Telephone: (800) MATTSON/(510) 657-5900. Internet: www.mattson.com

"Safe Harbor" Statement Under the Private Securities Litigation Reform Act of 1995: This news release contains forward-looking statements. Forward-looking statements address matters that are subject to a number of risks and uncertainties that can cause actual results to differ materially. Such risks and uncertainties include, but are not limited to: end-user demand for semiconductors; customer demand for semiconductor manufacturing equipment; the timing of significant customer orders for the Company's products; customer acceptance of delivered products and the Company's ability to collect amounts due upon shipment and upon acceptance; the Company's ability to timely manufacture, deliver and support ordered products; the Company's ability to bring new products to market and to gain market share with such products; customer rate of adoption of new technologies; risks inherent in the development of complex technology; the timing and competitiveness of new product

releases by the Company's competitors; the Company's ability to align its cost structure with market conditions; and other risks and uncertainties described in the Company's Forms 10-K, 10-Q and other filings with the Securities and Exchange Commission. The Company assumes no obligation to update the information provided in this news release.

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